

BEST-21503U 80g Lötflusmittel Lotpaste für die Reparatur von Mobiltelefonen

Spezifikationen:

Modell: BST-21503U

Volumen: 80g

Größe: 80 * 45mm

Meiting Poting: 60 °C

PRODUCT DISPLAY



PRODUCT DETAILS



Name: Soldering Paste

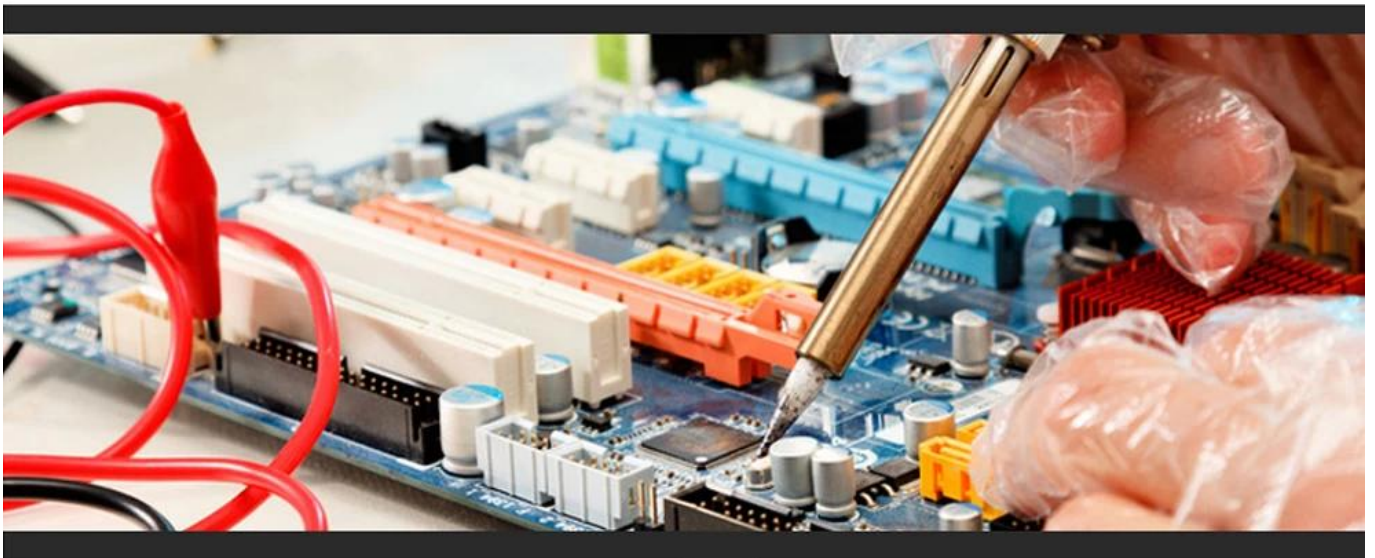
Size: $\Phi 80 \times 45$ mm

Composition: Solder powder, resin

Model: BST-21503U

Weight: 80g

Melting point: 60°C





- ▲ Stable performance, Not volatile, long life cycle, the amount of province;
- ▲ Non-toxic non-irritating odor, the use of safe and reliable;
- ▲ The IC and PCB are not corrosive
- ▲ Its boiling point is only slightly higher than the melting point of solder.

Features: Solder melting at the time of soldering begins to boil endothermic vaporization, which can be maintained at this temperature using IC and PCB temperatures. In the demolition of the chip with a lot of solder paste, it melts fast, you can flow to the BGA chip below. Rosin is solid without solder paste convenient.

PRODUCT PHOTOGRAPH



